

Amendments to the Claims

1. *(Currently Amended)* A method for patterning a surface ~~(52)~~ of a substrate ~~(50)~~ with an ink, the method comprising the steps of:

providing an elastomeric stamp ~~(10)~~ having a bulk surface ~~(12)~~ and at least one feature ~~(14, 14')~~ protruding from the bulk surface ~~(12)~~, the protruding feature ~~(14, 14')~~ having a contact surface ~~(16, 16')~~ and an edge ~~(18, 18')~~ extending extending from the contact surface ~~(16, 16')~~ to the bulk surface ~~(12)~~, the protruding feature ~~(14, 14')~~ and the bulk surface ~~(12)~~ carrying a barrier layer ~~(20)~~;

applying a solution of the ink and a solvent ~~(30)~~ to the barrier layer ~~(20)~~;

removing the solvent ~~(30)~~ from the barrier layer ~~(20)~~;

providing a first substrate ~~(40)~~ with a surface ~~(42)~~ having a higher affinity for the ink than the barrier layer ~~(20)~~;

contacting the contact surface ~~(16, 16')~~ of the protruding feature ~~(14, 14')~~ with the surface ~~(42)~~ of the first substrate ~~(40)~~;

transferring the ink from the contact surface ~~(16, 16')~~ of the protruding feature ~~(14, 14')~~ to the surface ~~(42)~~ of the first substrate ~~(40)~~;

removing the elastomeric stamp ~~(10)~~ from the surface ~~(42)~~ of the first substrate ~~(40)~~;

providing a second substrate ~~(50)~~ with a surface ~~(52)~~ having a higher affinity for the ink than the barrier layer ~~(20)~~;

contacting the contact surface ~~(16, 16')~~ of the protruding feature ~~(14, 14')~~ with the surface ~~(52)~~ of the second substrate ~~(50)~~; and

providing the surface ~~(52)~~ of the second substrate ~~(50)~~ with an ink pattern ~~(60)~~ by transferring the ink from the edge ~~(18, 18')~~ of the protruding feature ~~(14, 14')~~ to the surface ~~(52)~~ of the second substrate ~~(50)~~.

2. *(Currently Amended)* A method as claimed in claim 1, further comprising the step of removing a part of the surface ~~(52)~~ of the second substrate ~~(50)~~, the part being defined by the ink pattern ~~(60)~~.

3. *(Currently Amended)* A method as claimed in claim 2, wherein the removing of the part of the surface ~~(52)~~ of the second substrate ~~(50)~~ comprises an etching step.